

● Soldering and Mounting

The component cannot withstand washing.

● Storage and Operating Conditions

1. Product Storage Conditions

Please store the products in room where the temperature/humidity is stable, and avoid such places where there are large temperature changes. Please store the products under the following conditions:

Temperature: -10 to +40°C

Humidity: 15 to 85% R.H.

2. Expiration Date on Storage

Expiration date (Shelf life) of the products is six months after delivery under the conditions of a sealed and unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because the products may be degraded in solderability due to storage under poor conditions.

Please confirm solderability and characteristics for the products regularly.

3. Notice on Product Storage

(1) Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because quality and solderability may be degraded due to the storage in a chemical atmosphere.

- (2) Please do not put the products directly on the floor without anything under them to avoid damp places and/or dusty places.
- (3) Please do not store the products in the places such as a damp heated place or any place exposed to direct sunlight or excessive vibration.
- (4) Please use the products immediately after package is opened, because quality and solderability may be degraded due to storage under the poor conditions.
- (5) To avoid cracking of ceramic element, please do not drop the products.

4. Other

Please be sure to consult with our sales representative or engineer whenever the products are to be used in conditions not listed above.

● Rating

The component may be damaged if excessive mechanical stress is applied.

● Handling

1. Do not use this product with bend. The component may be damaged if excess mechanical stress is applied to it mounted on the printed circuit board.
2. Do not apply any type of reflow soldering on the component.
3. Do not clean or wash the component as it is not hermetically sealed.
4. Do not use strong acidity flux, more than 0.2wt% chlorine content, in flow soldering.
5. In case of overcoating the component, conditions such as material of resin, cure temperature, and so on should be evaluated well.
6. Accurate test circuit values are required to measure electrical characteristics. It may be a cause of miscorrelation if there is any deviation, especially stray capacitance, from the test circuit in the specification.
7. For safety purposes, avoid applying a direct current between the terminals.